Product Change Notification / RMES-21CWWT073

Date:

06-Dec-2021

Product Category:

Ethernet Bridges, Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4629 Final Notice: Qualification of STA as an additional assembly site for LAN7500x, LAN8820x and LAN9730x device families available in 56L VQFN (8x8x0.9mm) package.

Affected CPNs:

RMES-21CWWT073_Affected_CPN_12062021.pdf
RMES-21CWWT073_Affected_CPN_12062021.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of STA as an additional assembly site for LAN7500x, LAN8820x and LAN9730x device families available in 56L VQFN (8x8x0.9mm) package.

Pre and Post Change Summary:

	Pre Change	**Post Change**	
Assembly Site	ASE Inc.	ASE Inc.	STATS Chippac Ltd.

	(ASE)	(ASE)	(STA)
Wire Material	PdCu	PdCu	CuPdAu
Die Attach Material	EN-4900F	EN-4900F	8290
Molding Compound Material	G631B	G631B	G700E
Lead-Frame Material	C194	C194	C194
Lead-Frame Paddle Size	240X240 mils	240X240 mils	236X236 mils
DAP Surface Prep	Double Ring	Double Ring	Double Ring

Impacts to Data Sheet: None

Change Impact None

Reason for Change: To improve manufacturability by qualifying STA as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: October 31, 2021 (date code: 2145)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2021					**>**	**October 2021**						**December 2021**			
Workweek	14	15	16	17	18		40	41	42	43	44	45	49	50	51	52
Initial PCN Issue Date				x												
Qual Report Availability														x		
Final PCN Issue Date							x									
Estimated Implementation Date												x				

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:
April 22, 2021: Issued initial notification.
October 01, 2021: Issued final notification. Provided estimated first ship date to be on October 31, 2021. Updated the estimated qualification completion date from August 2021 to December 2021. Updated the lead frame DAP surface prep of STA assembly site from Ring plating to double ring plating in the pre and post change summary table. Attached the lead frame drawing pre and post change summary.
December 6, 2021: Re-issued final notification. Updated the lead frame drawing pre and post change summary. Attached the qualification report and updated time table summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_RMES-21CWWT073_Qual_Report.pdf
PCN_RMES-21CWWT073_ Pre and Post Change_Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.